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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	C166
Core Size	16-Bit
Speed	20MHz
Connectivity	EBI/EMI, I²C, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	76
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	PG-TQFP-100-1
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/c161pilfcabxuma1

Pin Configuration TQFP Package

(top view)

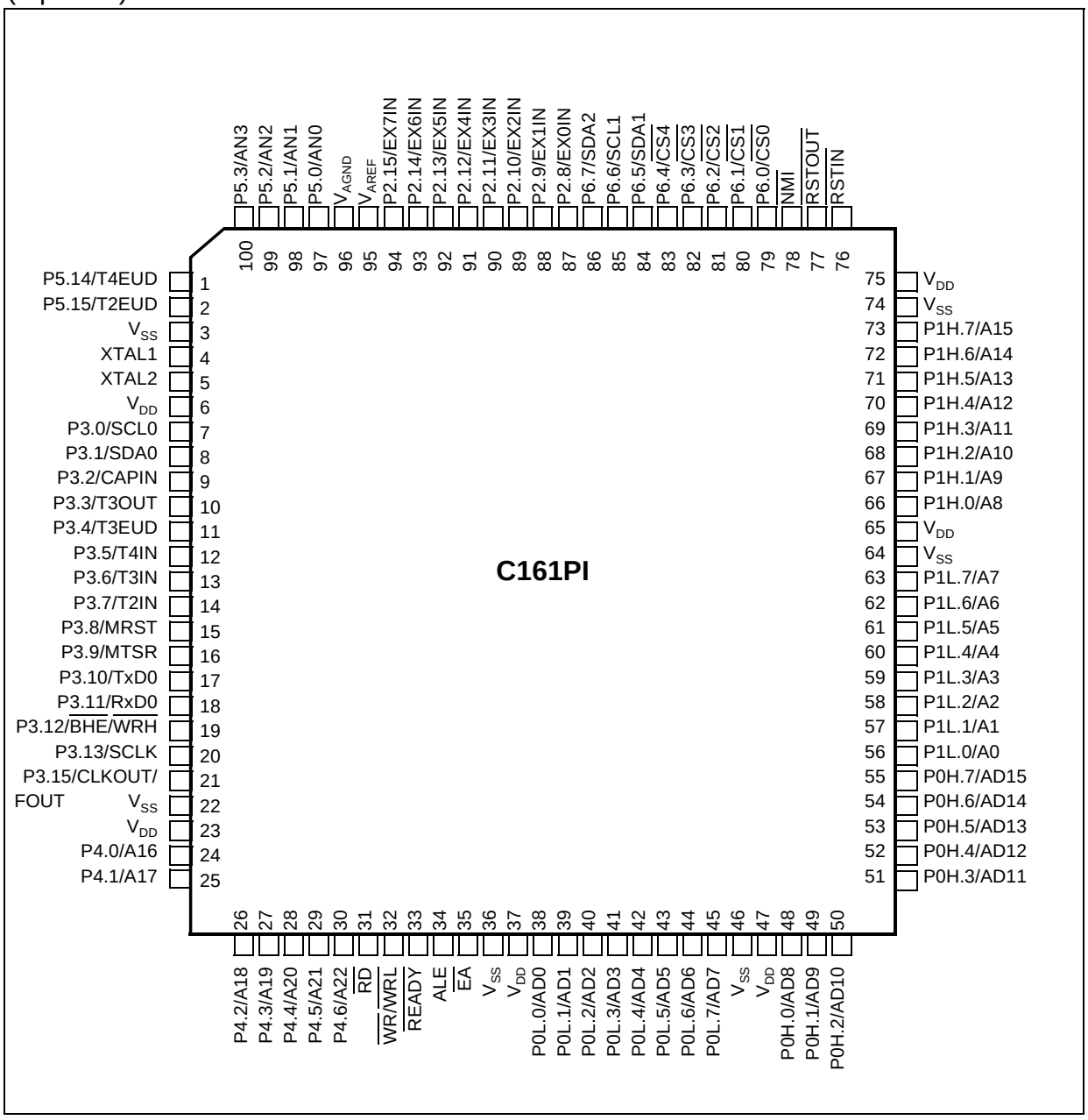

Figure 3

Table 1 Pin Definitions and Functions (continued)

Symbol	Pin Num. TQFP	Pin Num. MQFP	Input Outp.	Function	
P3			IO	Port 3 is a 15-bit bidirectional I/O port. It is bit-wise programmable for input or output via direction bits. For a pin configured as input, the output driver is put into high-impedance state. Port 3 outputs can be configured as push/pull or open drain drivers. The input threshold of Port 3 is selectable (TTL or special). The following Port 3 pins also serve for alternate functions:	
P3.0	7	9	I/O	SCL0	I2C Bus Clock Line 0
P3.1	8	10	I/O	SDA0	I2C Bus Data Line 0
P3.2	9	11	I	CAPIN	GPT2 Register CAPREL Capture Input
P3.3	10	12	O	T3OUT	GPT1 Timer T3 Toggle Latch Output
P3.4	11	13	I	T3EUD	GPT1 Timer T3 External Up/Down Ctrl.Inp
P3.5	12	14	I	T4IN	GPT1 Timer T4 Count/Gate/Reload/ Capture Input
P3.6	13	15	I	T3IN	GPT1 Timer T3 Count/Gate Input
P3.7	14	16	I	T2IN	GPT1 Timer T2 Count/Gate/Reload/ Capture Input
P3.8	15	17	I/O	MRST	SSC Master-Rec. / Slave-Trans. Inp/Outp.
P3.9	16	18	I/O	MTSR	SSC Master-Trans. / Slave-Rec. Outp/Inp.
P3.10	17	19	O	T×D0	ASC0 Clock/Data Output (Async./Sync.)
P3.11	18	20	I/O	R×D0	ASC0 Data Input (Async.) or I/O (Sync.)
P3.12	19	21	O	$\overline{\text{BHE}}$	External Memory High Byte Enable Signal,
			O	$\overline{\text{WRH}}$	External Memory High Byte Write Strobe
P3.13	20	22	I/O	SCLK	SSC Master Clock Outp. / Slave Clock Inp.
P3.15	21	23	O	CLKOUT	System Clock Output (=CPU Clock)
			O	FOUT	Programmable Frequency Output
				Note: Pins P3.0 and P3.1 are open drain outputs only.	

Table 1 Pin Definitions and Functions (continued)

Symbol	Pin Num. TQFP	Pin Num. MQFP	Input Outp.	Function
$\overline{\text{RSTIN}}$	76	78	I/O	Reset Input with Schmitt-Trigger characteristics. A low level at this pin while the oscillator is running resets the C161PI. An internal pullup resistor permits power-on reset using only a capacitor connected to V_{SS}. A spike filter suppresses input pulses <10 ns. Input pulses >100 ns safely pass the filter. The minimum duration for a safe recognition should be 100 ns + 2 CPU clock cycles. In bidirectional reset mode (enabled by setting bit BDRSTEN in register SYSCON) the $\overline{\text{RSTIN}}$ line is internally pulled low for the duration of the internal reset sequence upon any reset (HW, SW, WDT). See note below this table. *Note: To let the reset configuration of PORT0 settle and to let the PLL lock a reset duration of ca. 1 ms is recommended.*
$\overline{\text{RSTOUT}}$	77	79	O	Internal Reset Indication Output. This pin is set to a low level when the part is executing either a hardware-, a software- or a watchdog timer reset. $\overline{\text{RSTOUT}}$ remains low until the EINIT (end of initialization) instruction is executed.
$\overline{\text{NMI}}$	78	80	I	Non-Maskable Interrupt Input. A high to low transition at this pin causes the CPU to vector to the NMI trap routine. When the PWRDN (power down) instruction is executed, the $\overline{\text{NMI}}$ pin must be low in order to force the C161PI to go into power down mode. If $\overline{\text{NMI}}$ is high, when PWRDN is executed, the part will continue to run in normal mode. If not used, pin $\overline{\text{NMI}}$ should be pulled high externally.

Table 1 Pin Definitions and Functions (continued)

Symbol	Pin Num. TQFP	Pin Num. MQFP	Input Outp.	Function
P6			IO	Port 6 is an 8-bit bidirectional I/O port. It is bit-wise programmable for input or output via direction bits. For a pin configured as input, the output driver is put into high-impedance state. Port 6 outputs can be configured as push/pull or open drain drivers. The Port 6 pins also serve for alternate functions:
P6.0	79	81	O	$\overline{CS0}$ Chip Select 0 Output
P6.1	80	82	O	$\overline{CS1}$ Chip Select 1 Output
P6.2	81	83	O	$\overline{CS2}$ Chip Select 2 Output
P6.3	82	84	O	$\overline{CS3}$ Chip Select 3 Output
P6.4	83	85	O	CS4 Chip Select 4 Output
P6.5	84	86	I/O	SDA1 I^2C Bus Data Line 1
P6.6	85	87	I/O	SCL1 I^2C Bus Clock Line 1
P6.7	86	88	I/O	SDA2 I^2C Bus Data Line 2
				Note: Pins P6.7-5 are open drain outputs only.
P2			IO	Port 2 is an 8-bit bidirectional I/O port. It is bit-wise programmable for input or output via direction bits. For a pin configured as input, the output driver is put into high-impedance state. Port 2 outputs can be configured as push/pull or open drain drivers. The input threshold of Port 2 is selectable (TTL or special). The Port 2 pins also serve for alternate functions:
P2.8	87	89	I	EX0IN Fast External Interrupt 0 Input
P2.9	88	90	I	EX1IN Fast External Interrupt 1 Input
P2.10	89	91	I	EX2IN Fast External Interrupt 2 Input
P2.11	90	92	I	EX3IN Fast External Interrupt 3 Input
P2.12	91	93	I	EX4IN Fast External Interrupt 4 Input
P2.13	92	94	I	EX5IN Fast External Interrupt 5 Input
P2.14	93	95	I	EX6IN Fast External Interrupt 6 Input
P2.15	94	96	I	EX7IN Fast External Interrupt 7 Input
V_{AREF}	95	97	-	Reference voltage for the A/D converter.
V_{AGND}	96	98	-	Reference ground for the A/D converter.

Table 1 Pin Definitions and Functions (continued)

Symbol	Pin Num. TQFP	Pin Num. MQFP	Input Outp.	Function
V_{DD}	6, 23, 37, 47, 65, 75	8, 25, 39, 49, 67, 77	-	Digital Supply Voltage: + 5 V or + 3 V during normal operation and idle mode. ≥ 2.5 V during power down mode
V_{SS}	3, 22, 36, 46, 64, 74	5, 24, 38, 48, 66, 76	-	Digital Ground.

Note: The following behaviour differences must be observed when the bidirectional reset is active:

- Bit BDRSTEN in register SYSCON cannot be changed after EINIT and is cleared automatically after a reset.
- The reset indication flags always indicate a long hardware reset.
- The PORT0 configuration is treated like on a hardware reset. Especially the bootstrap loader may be activated when P0L.4 is low.
- Pin $\overline{\text{RSTIN}}$ may only be connected to external reset devices with an open drain output driver.
- A short hardware reset is extended to the duration of the internal reset sequence.

Functional Description

The architecture of the C161PI combines advantages of both RISC and CISC processors and of advanced peripheral subsystems in a very well-balanced way. The following block diagram gives an overview of the different on-chip components and of the advanced, high bandwidth internal bus structure of the C161PI.

Note: All time specifications refer to a CPU clock of 25 MHz (see definition in the AC Characteristics section).

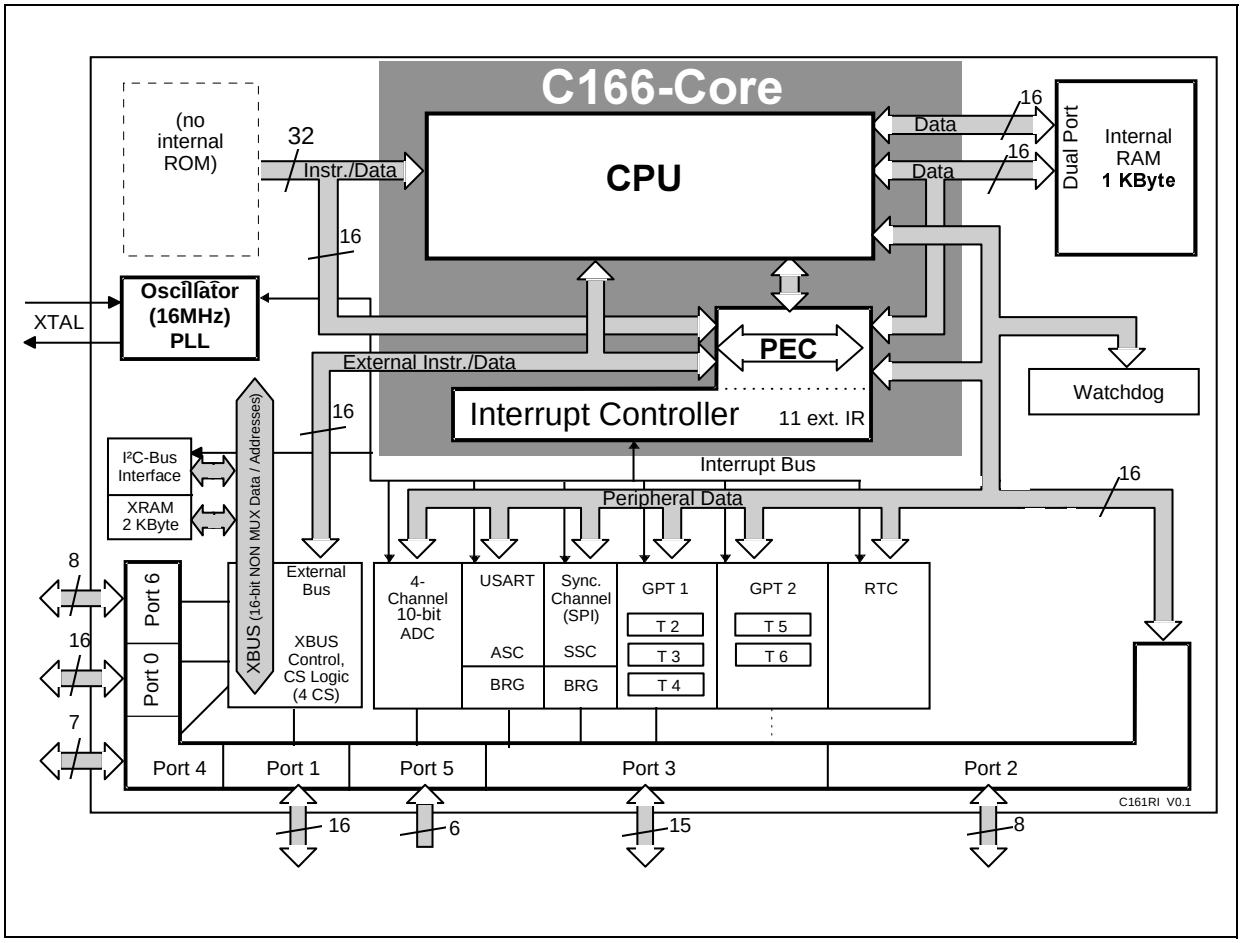

Figure 4 Block Diagram

Memory Organization

The memory space of the C161PI is configured in a Von Neumann architecture which means that code memory, data memory, registers and I/O ports are organized within the same linear address space which includes 16 MBytes. The entire memory space can be accessed bytewise or wordwise. Particular portions of the on-chip memory have additionally been made directly bitaddressable.

1 KByte of on-chip Internal RAM (IRAM) is provided as a storage for user defined variables, for the system stack, general purpose register banks and even for code. A register bank can consist of up to 16 wordwide (R0 to R15) and/or bytewide (RL0, RH0, …, RL7, RH7) so-called General Purpose Registers (GPRs).

1024 bytes (2 * 512 bytes) of the address space are reserved for the Special Function Register areas (SFR space and ESFR space). SFRs are wordwide registers which are used for controlling and monitoring functions of the different on-chip units. Unused SFR addresses are reserved for future members of the C166 Family.

2 KBytes of on-chip Extension RAM (XRAM) are provided to store user data, user stacks, or code. The XRAM is accessed like external memory and therefore cannot be used for the system stack or for register banks and is not bitaddressable. The XRAM permits 16-bit accesses with maximum speed.

In order to meet the needs of designs where more memory is required than is provided on chip, up to 8 MBytes of external RAM and/or ROM can be connected to the microcontroller.

External Bus Controller

All of the external memory accesses are performed by a particular on-chip External Bus Controller (EBC). It can be programmed either to Single Chip Mode when no external memory is required, or to one of four different external memory access modes, which are as follows:

– 16-/18-/20-/23-bit Addresses, 16-bit Data, Demultiplexed
– 16-/18-/20-/23-bit Addresses, 16-bit Data, Multiplexed
– 16-/18-/20-/23-bit Addresses, 8-bit Data, Multiplexed
– 16-/18-/20-/23-bit Addresses, 8-bit Data, Demultiplexed

In the demultiplexed bus modes, addresses are output on PORT1 and data is input/ output on PORT0 or P0L, respectively. In the multiplexed bus modes both addresses and data use PORT0 for input/output.

Important timing characteristics of the external bus interface (Memory Cycle Time, Memory Tri-State Time, Length of ALE and Read Write Delay) have been made programmable to allow the user the adaption of a wide range of different types of memories and external peripherals.
In addition, up to 4 independent address windows may be defined (via register pairs ADDRSELx / BUSCONx) which allow to access different resources with different bus characteristics. These address windows are arranged hierarchically where BUSCON4 overrides BUSCON3 and BUSCON2 overrides BUSCON1. All accesses to locations not covered by these 4 address windows are controlled by BUSCON0.
Up to 5 external $\overline{CS}$ signals (4 windows plus default) can be generated in order to save external glue logic. The C161PI offers the possibility to switch the $\overline{CS}$ outputs to an unlatched mode. In this mode the internal filter logic is switched off and the $\overline{CS}$ signals are directly generated from the address. The unlatched $\overline{CS}$ mode is enabled by setting CSCFG (SYSCON.6).

Access to very slow memories is supported via a particular ‘Ready’ function.

For applications which require less than 8 MBytes of external memory space, this address space can be restricted to 1 MByte, 256 KByte or to 64 KByte. In this case Port 4 outputs four, two or no address lines at all. It outputs all 7 address lines, if an address space of 8 MBytes is used.

Serial Channels

Serial communication with other microcontrollers, processors, terminals or external peripheral components is provided by two serial interfaces with different functionality, an Asynchronous/Synchronous Serial Channel (**ASC0**) and a High-Speed Synchronous Serial Channel (**SSC**).

The ASC0 is upward compatible with the serial ports of the Infineon 8-bit microcontroller families and supports full-duplex asynchronous communication at up to 780 KBaud and half-duplex synchronous communication at up to 3.1 MBaud @ 25 MHz CPU clock.
A dedicated baud rate generator allows to set up all standard baud rates without oscillator tuning. For transmission, reception and error handling 4 separate interrupt vectors are provided. In asynchronous mode, 8- or 9-bit data frames are transmitted or received, preceded by a start bit and terminated by one or two stop bits. For multiprocessor communication, a mechanism to distinguish address from data bytes has been included (8-bit data plus wake up bit mode).
In synchronous mode, the ASC0 transmits or receives bytes (8 bits) synchronously to a shift clock which is generated by the ASC0. The ASC0 always shifts the LSB first. A loop back option is available for testing purposes.
A number of optional hardware error detection capabilities has been included to increase the reliability of data transfers. A parity bit can automatically be generated on transmission or be checked on reception. Framing error detection allows to recognize data frames with missing stop bits. An overrun error will be generated, if the last character received has not been read out of the receive buffer register at the time the reception of a new character is complete.

The SSC supports full-duplex synchronous communication at up to 6.25 Mbaud @ 25 MHz CPU clock. It may be configured so it interfaces with serially linked peripheral components. A dedicated baud rate generator allows to set up all standard baud rates without oscillator tuning. For transmission, reception and error handling 3 separate interrupt vectors are provided.
The SSC transmits or receives characters of 2...16 bits length synchronously to a shift clock which can be generated by the SSC (master mode) or by an external master (slave mode). The SSC can start shifting with the LSB or with the MSB and allows the selection of shifting and latching clock edges as well as the clock polarity.
A number of optional hardware error detection capabilities has been included to increase the reliability of data transfers. Transmit and receive error supervise the correct handling of the data buffer. Phase and baudrate error detect incorrect serial data.

Table 4 Instruction Set Summary (continued)

Mnemonic	Description	Bytes
MOV(B)	Move word (byte) data	2 / 4
MOVBS	Move byte operand to word operand with sign extension	2 / 4
MOVBZ	Move byte operand to word operand. with zero extension	2 / 4
JMPA, JMPI, JMPR	Jump absolute/indirect/relative if condition is met	4
JMPS	Jump absolute to a code segment	4
J(N)B	Jump relative if direct bit is (not) set	4
JBC	Jump relative and clear bit if direct bit is set	4
JNBS	Jump relative and set bit if direct bit is not set	4
CALLA, CALLI, CALLR	Call absolute/indirect/relative subroutine if condition is met	4
CALLS	Call absolute subroutine in any code segment	4
PCALL	Push direct word register onto system stack and call absolute subroutine	4
TRAP	Call interrupt service routine via immediate trap number	2
PUSH, POP	Push/pop direct word register onto/from system stack	2
SCXT	Push direct word register onto system stack und update register with word operand	4
RET	Return from intra-segment subroutine	2
RETS	Return from inter-segment subroutine	2
RETP	Return from intra-segment subroutine and pop direct word register from system stack	2
RETI	Return from interrupt service subroutine	2
SRST	Software Reset	4
IDLE	Enter Idle Mode	4
PWRDN	Enter Power Down Mode (supposes $\overline{\text{NMI}}$-pin being low)	4
SRVWDT	Service Watchdog Timer	4
DISWDT	Disable Watchdog Timer	4
EINIT	Signify End-of-Initialization on RSTOUT-pin	4
ATOMIC	Begin ATOMIC sequence	2
EXTR	Begin EXTended Register sequence	2
EXTP(R)	Begin EXTended Page (and Register) sequence	2 / 4
EXTS(R)	Begin EXTended Segment (and Register) sequence	2 / 4
NOP	Null operation	2

Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation of the C161PI. All parameters specified in the following sections refer to these operating conditions, unless otherwise noticed.

Table 7 Operating Condition Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Standard digital supply voltage	V_{DD}	4.5	5.5	V	Active mode, f_{CPUmax} = 25 MHz
		2.5 [1]	5.5	V	PowerDown mode
Reduced digital supply voltage	V_{DD}	3.0	3.6	V	Active mode, f_{CPUmax} = 20 MHz
		2.5 [1]	3.6	V	PowerDown mode
Digital ground voltage	V_{SS}	0		V	Reference voltage
Overload current	I_{OV}	-	±5	mA	Per pin [2] [3]
Absolute sum of overload currents	$\Sigma\|I_{OV}\|$	-	50	mA	[3]
External Load Capacitance	C_L	-	100	pF	Pin drivers in **fast edge** mode (PDCR.BIPEC = '0')
		-	50	pF	Pin drivers in **reduced edge** mode (PDCR.BIPEC = '1') [3]
Ambient temperature	T_A	0	70	°C	SAB-C161PI...
		-40	85	°C	SAF-C161PI...
		-40	125	°C	SAK-C161PI...

1) Output voltages and output currents will be reduced when V_{DD} leaves the range defined for active mode.

2) Overload conditions occur if the standard operatings conditions are exceeded, i.e. the voltage on any pin exceeds the specified range (i.e. $V_{OV} > V_{DD}$+0.5V or $V_{OV} < V_{SS}$-0.5V). The absolute sum of input overload currents on all port pins may not exceed **50 mA**. The supply voltage must remain within the specified limits.

3) Not 100% tested, guaranteed by design characterization.

DC Characteristics (Standard Supply Voltage Range) (continued)
(Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Power-down mode supply current (5V) with RTC running	I_{PDR5} 8)	–	200 + 25*f_{OSC}	µA	$V_{DD} = V_{DDmax}$ f_{OSC} in [MHz] 9)
Power-down mode supply current (5V) with RTC disabled	I_{PDO5}	–	50	µA	$V_{DD} = V_{DDmax}$ 9)

1) This specification is not valid for outputs which are switched to open drain mode. In this case the respective output will float and the voltage results from the external circuitry.

2) These parameters describe the $\overline{\text{RSTIN}}$ pullup, which equals a resistance of ca. 50 to 250 KΩ.

3) The maximum current may be drawn while the respective signal line remains inactive.

4) The minimum current must be drawn in order to drive the respective signal line active.

5) This specification is only valid during Reset, or during Hold- or Adapt-mode. During Hold mode Port 6 pins are only affected, if they are used (configured) for $\overline{\text{CS}}$ output and the open drain function is not enabled.

6) Not 100% tested, guaranteed by design characterization.

7) The supply current is a function of the operating frequency. This dependency is illustrated in the figure below. These parameters are tested at V_{DDmax} and maximum CPU clock with all outputs disconnected and all inputs at V_{IL} or V_{IH}.
The oscillator also contributes to the total supply current. The given values refer to the worst case, ie. I_{PDRmax}. For lower oscillator frequencies the respective supply current can be reduced accordingly.

8) This parameter is determined mainly by the current consumed by the oscillator. This current, however, is influenced by the external oscillator circuitry (crystal, capacitors). The values given refer to a typical circuitry and may change in case of a not optimized external oscillator circuitry.

9) This parameter is tested including leakage currents. All inputs (including pins configured as inputs) at 0 V to 0.1 V or at V_{DD} – 0.1 V to V_{DD}, V_{REF} = 0 V, all outputs (including pins configured as outputs) disconnected.

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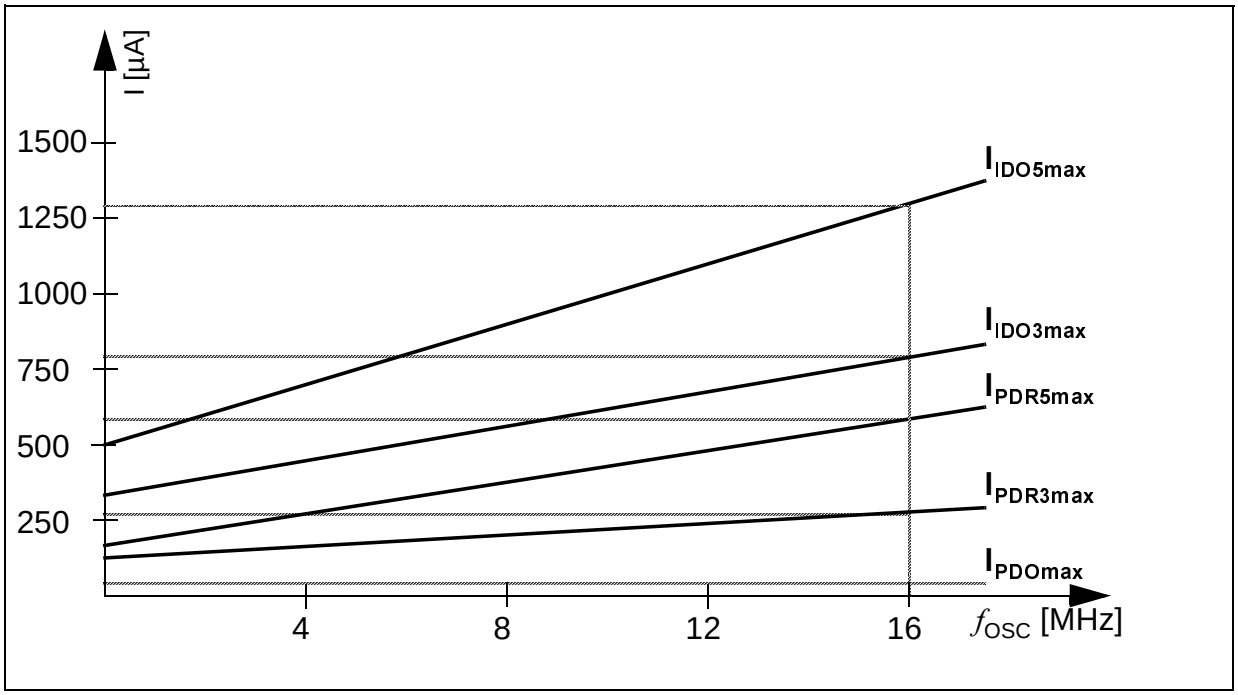


Figure 9 Idle and Power Down Supply Current as a Function of Oscillator Frequency

AC Characteristics
Definition of Internal Timing

The internal operation of the C161PI is controlled by the internal CPU clock f_{CPU}. Both edges of the CPU clock can trigger internal (e.g. pipeline) or external (e.g. bus cycles) operations.

The specification of the external timing (AC Characteristics) therefore depends on the time between two consecutive edges of the CPU clock, called “TCL” (see figure below).

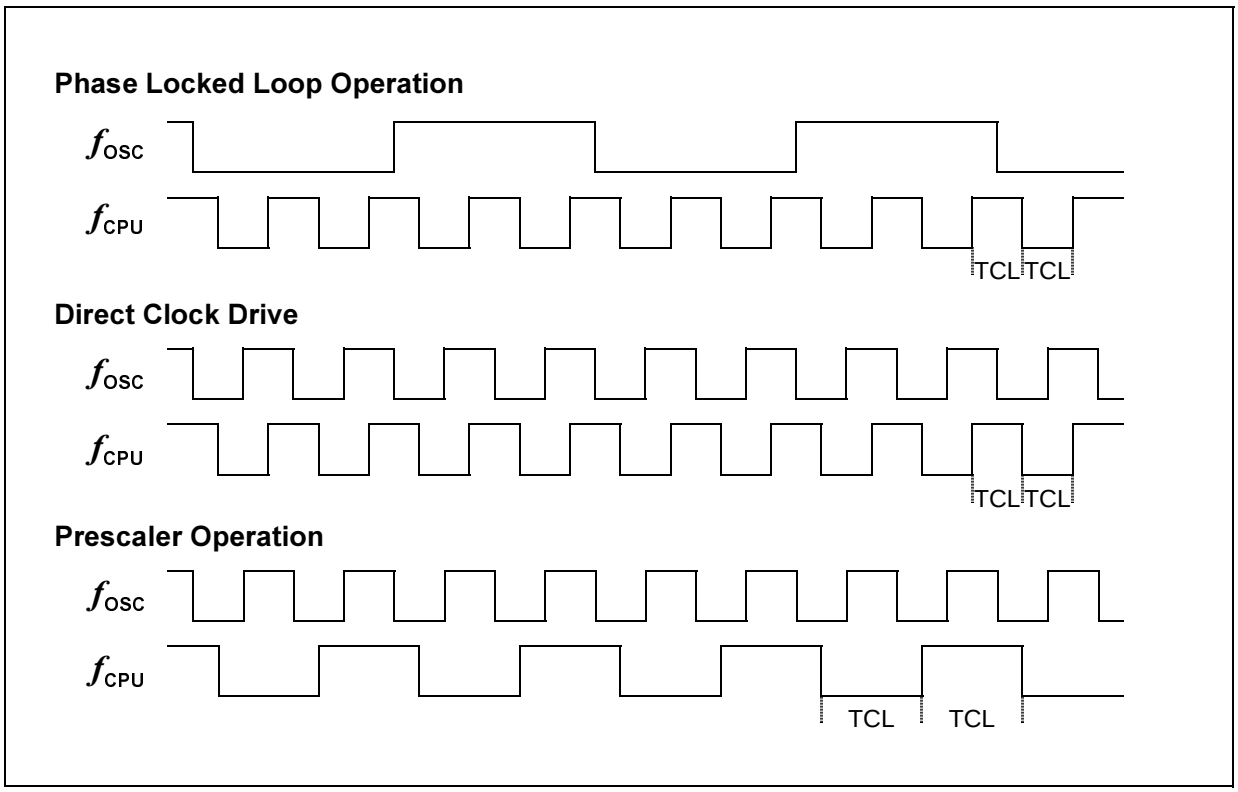


Figure 11 Generation Mechanisms for the CPU Clock

The CPU clock signal f_{CPU} can be generated from the oscillator clock signal f_{OSC} via different mechanisms. The duration of TCLs and their variation (and also the derived external timing) depends on the used mechanism to generate f_{CPU}. This influence must be regarded when calculating the timings for the C161PI.

Note: The example for PLL operation shown in the fig. above refers to a PLL factor of 4.

The used mechanism to generate the CPU clock is selected during reset via the logic levels on pins P0.15-13 (P0H.7-5).

The table below associates the combinations of these three bits with the respective clock generation mode.

Multiplexed Bus (Standard Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 6 TCL + $2t_A$ + t_C + t_F (120 ns at 25 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
			min.	max.	min.	max.	
Data valid to $\overline{WR}$	t_{22}	CC	20 + t_C	–	2TCL - 20 + t_C	–	ns
Data hold after $\overline{WR}$	t_{23}	CC	26 + t_F	–	2TCL - 14 + t_F	–	ns
ALE rising edge after $\overline{RD}$, $\overline{WR}$	t_{25}	CC	26 + t_F	–	2TCL - 14 + t_F	–	ns
Address hold after $\overline{RD}$, $\overline{WR}$	t_{27}	CC	26 + t_F	–	2TCL - 14 + t_F	–	ns
ALE falling edge to $\overline{CS}$ [1]	t_{38}	CC	-4 - t_A	10 - t_A	-4 - t_A	10 - t_A	ns
$\overline{CS}$ low to Valid Data In [1]	t_{39}	SR	–	40 + t_C + $2t_A$	–	3TCL - 20 + t_C + $2t_A$	ns
$\overline{CS}$ hold after $\overline{RD}$, $\overline{WR}$ [1]	t_{40}	CC	46 + t_F	–	3TCL - 14 +t_F	–	ns
ALE fall. edge to $\overline{RdCS}$, $\overline{WrCS}$ (with RW delay)	t_{42}	CC	16 + t_A	–	TCL - 4 + t_A	–	ns
ALE fall. edge to $\overline{RdCS}$, $\overline{WrCS}$ (no RW delay)	t_{43}	CC	-4 + t_A	–	-4 + t_A	–	ns
Address float after $\overline{RdCS}$, $\overline{WrCS}$ (with RW delay)	t_{44}	CC	–	0	–	0	ns
Address float after $\overline{RdCS}$, $\overline{WrCS}$ (no RW delay)	t_{45}	CC	–	20	–	TCL	ns
$\overline{RdCS}$ to Valid Data In (with RW delay)	t_{46}	SR	–	16 + t_C	–	2TCL - 24 + t_C	ns
$\overline{RdCS}$ to Valid Data In (no RW delay)	t_{47}	SR	–	36 + t_C	–	3TCL - 24 + t_C	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (with RW delay)	t_{48}	CC	30 + t_C	–	2TCL - 10 + t_C	–	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (no RW delay)	t_{49}	CC	50 + t_C	–	3TCL - 10 + t_C	–	ns

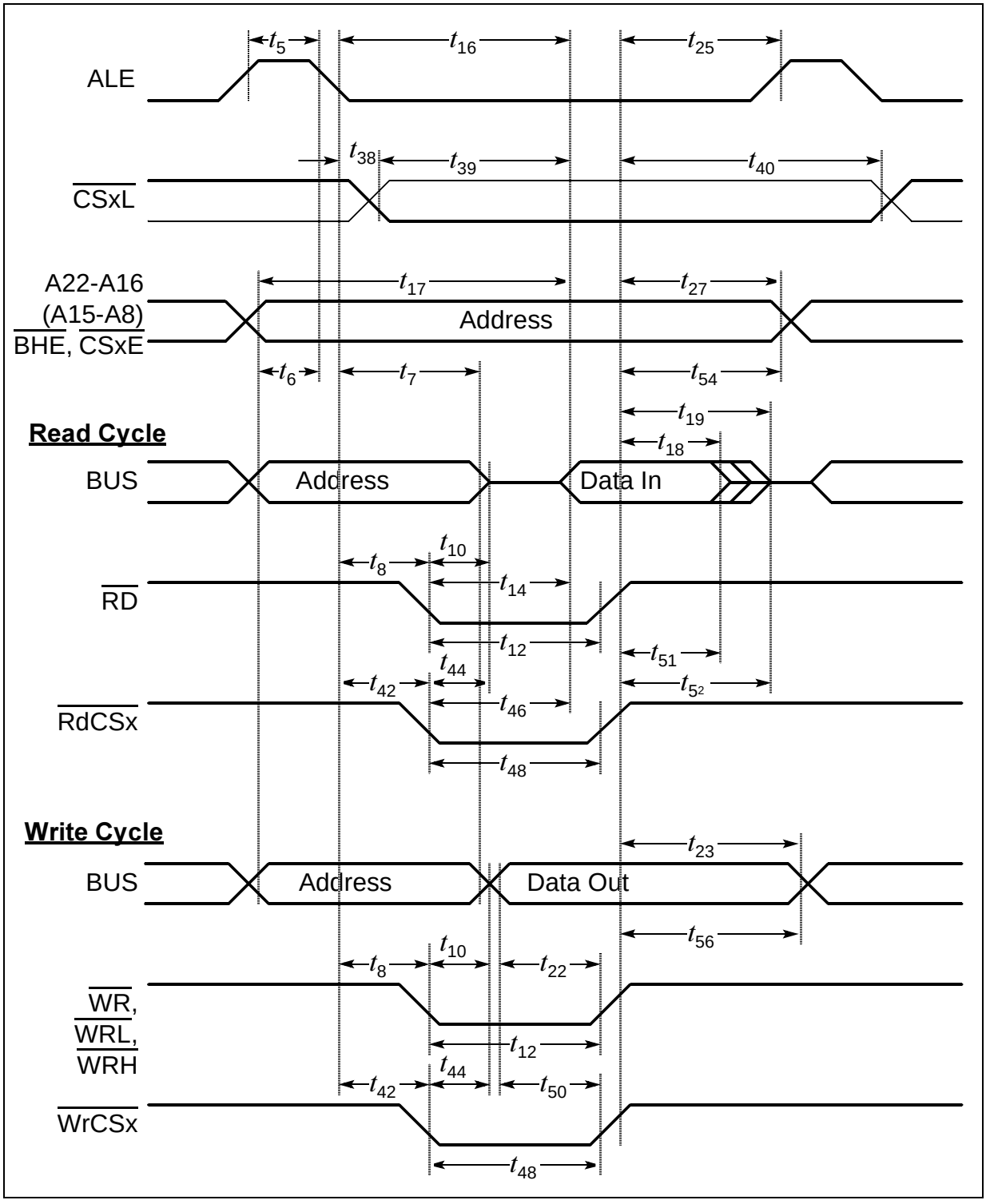


Figure 16 External Memory Cycle: Multiplexed Bus, With Read/Write Delay, Normal ALE

Demultiplexed Bus (Standard Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 4 TCL + 2t_A + t_C + t_F (80 ns at 25 MHz CPU clock without waitstates)

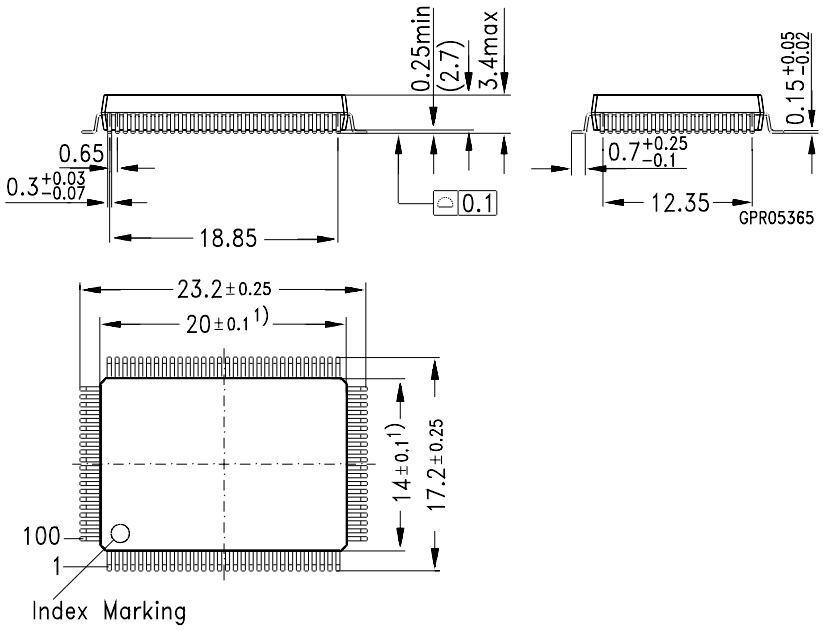
Parameter	Symbol		Max. CPU Clock = 25 MHz		Variable CPU Clock 1 / 2TCL = 1 to 25 MHz		Unit
			min.	max.	min.	max.	
Data hold after $\overline{WR}$	t_{24}	CC	10 + t_F	–	TCL - 10 + t_F	–	ns
$\overline{ALE}$ rising edge after $\overline{RD}$, $\overline{WR}$	t_{26}	CC	-10 + t_F	–	-10 + t_F	–	ns
Address hold after $\overline{WR}$ [2]	t_{28}	CC	0 + t_F	–	0 + t_F	–	ns
$\overline{ALE}$ falling edge to $\overline{CS}$ [3]	t_{38}	CC	-4 - t_A	10 - t_A	-4 - t_A	10 - t_A	ns
$\overline{CS}$ low to Valid Data In [3]	t_{39}	SR	–	40 + t_C + 2t_A	–	3TCL - 20 + t_C + 2t_A	ns
$\overline{CS}$ hold after $\overline{RD}$, $\overline{WR}$ [3]	t_{41}	CC	6 + t_F	–	TCL - 14 + t_F	–	ns
$\overline{ALE}$ falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (with RW-delay)	t_{42}	CC	16 + t_A	–	TCL - 4 + t_A	–	ns
$\overline{ALE}$ falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (no RW-delay)	t_{43}	CC	-4 + t_A	–	-4 + t_A	–	ns
$\overline{RdCS}$ to Valid Data In (with RW-delay)	t_{46}	SR	–	16 + t_C	–	2TCL - 24 + t_C	ns
$\overline{RdCS}$ to Valid Data In (no RW-delay)	t_{47}	SR	–	36 + t_C	–	3TCL - 24 + t_C	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (with RW-delay)	t_{48}	CC	30 + t_C	–	2TCL - 10 + t_C	–	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (no RW-delay)	t_{49}	CC	50 + t_C	–	3TCL - 10 + t_C	–	ns
Data valid to $\overline{WrCS}$	t_{50}	CC	26 + t_C	–	2TCL - 14 + t_C	–	ns
Data hold after $\overline{RdCS}$	t_{51}	SR	0	–	0	–	ns
Data float after $\overline{RdCS}$ (with RW-delay) [1]	t_{53}	SR	–	20 + t_F	–	2TCL - 20 + 2t_A + t_F [1]	ns
Data float after $\overline{RdCS}$ (no RW-delay) [1]	t_{68}	SR	–	0 + t_F	–	TCL - 20 + 2t_A + t_F [1]	ns

Demultiplexed Bus (Reduced Supply Voltage Range) (continued)
(Operating Conditions apply)
ALE cycle time = 4 TCL + 2t_A + t_C + t_F (100 ns at 20 MHz CPU clock without waitstates)

Parameter	Symbol		Max. CPU Clock = 20 MHz		Variable CPU Clock 1 / 2TCL = 1 to 20 MHz		Unit
			min.	max.	min.	max.	
Data hold after $\overline{WR}$	t_{24}	CC	15 + t_F	–	TCL - 10 + t_F	–	ns
$\overline{ALE}$ rising edge after $\overline{RD}$, $\overline{WR}$	t_{26}	CC	-12 + t_F	–	-12 + t_F	–	ns
Address hold after $\overline{WR}$ [2]	t_{28}	CC	0 + t_F	–	0 + t_F	–	ns
$\overline{ALE}$ falling edge to $\overline{CS}$ [3]	t_{38}	CC	-8 - t_A	10 - t_A	-8 - t_A	10 - t_A	ns
$\overline{CS}$ low to Valid Data In [3]	t_{39}	SR	–	47 + t_C + 2t_A	–	3TCL - 28 + t_C + 2t_A	ns
$\overline{CS}$ hold after $\overline{RD}$, $\overline{WR}$ [3]	t_{41}	CC	9 + t_F	–	TCL - 16 + t_F	–	ns
$\overline{ALE}$ falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (with RW-delay)	t_{42}	CC	19 + t_A	–	TCL - 6 + t_A	–	ns
$\overline{ALE}$ falling edge to $\overline{RdCS}$, $\overline{WrCS}$ (no RW-delay)	t_{43}	CC	-6 + t_A	–	-6 + t_A	–	ns
$\overline{RdCS}$ to Valid Data In (with RW-delay)	t_{46}	SR	–	20 + t_C	–	2TCL - 30 + t_C	ns
$\overline{RdCS}$ to Valid Data In (no RW-delay)	t_{47}	SR	–	45 + t_C	–	3TCL - 30 + t_C	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (with RW-delay)	t_{48}	CC	38 + t_C	–	2TCL - 12 + t_C	–	ns
$\overline{RdCS}$, $\overline{WrCS}$ Low Time (no RW-delay)	t_{49}	CC	63 + t_C	–	3TCL - 12 + t_C	–	ns
Data valid to $\overline{WrCS}$	t_{50}	CC	28 + t_C	–	2TCL - 22 + t_C	–	ns
Data hold after $\overline{RdCS}$	t_{51}	SR	0	–	0	–	ns
Data float after $\overline{RdCS}$ (with RW-delay) [1]	t_{53}	SR	–	30 + t_F	–	2TCL - 20 + 2t_A + t_F [1]	ns
Data float after $\overline{RdCS}$ (no RW-delay) [1]	t_{68}	SR	–	5 + t_F	–	TCL - 20 + 2t_A + t_F [1]	ns

Package Outlines

Plastic Package, P-MQFP-100-2 (SMD)
(Plastic Metric Quad Flat Package)



1) Does not include plastic or metal protrusions of 0.25max per side

Figure 25

Package Outlines (continued)

Plastic Package, P-TQFP-100-1 (SMD)
(Plastic Thin Metric Quad Flat Package)

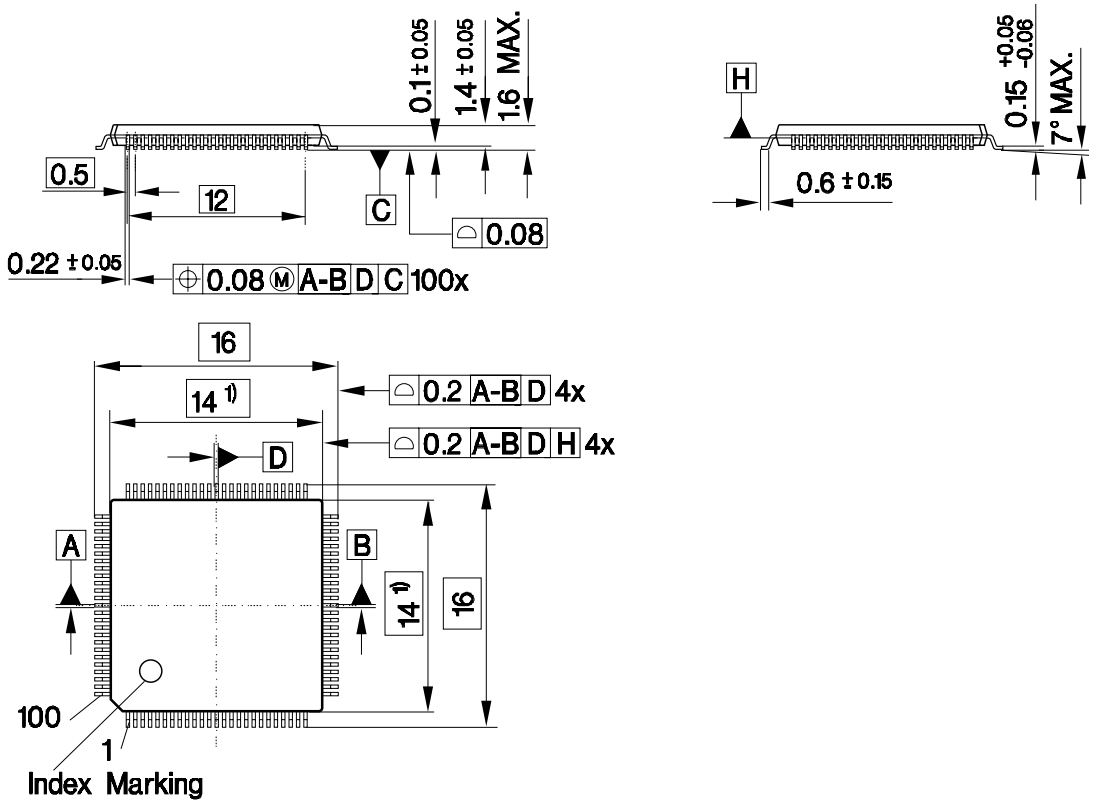


Figure 26

Sorts of Packing

Package outlines for tubes, trays, etc. are contained in our Data Book “Package Information”

SMD = Surface Mounted Device

Dimensions in mm